Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.018”**



**.018”**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: E = .0027” B = .0031”**

**Backside Potential: Collector**

**Mask Ref: 07**

**APPROVED BY: DK DIE SIZE .018” X .018” DATE: 1/26/22**

**MFG: FAIRCHILD / NSC THICKNESS .008” P/N: 2N2484**

**DG 10.1.2**

#### Rev B, 7/19/02